

WATOV & KIPNESA PROFESSIONAL CORPORATION
ATTORNEYS AT LAWKENNETH WATOV* (NJ and NY)
ALLEN R. KIPNES (NY)
ALBERT H. HSU (NJ, NY, AND DC)Mailing Address:
P.O. BOX 247
PRINCETON JUNCTION, NJ 08550PATENTS, TRADEMARKS,
COPYRIGHTS AND
RELATED MATTERSE-Mail for KW-WKKen@aol.com
E-Mail for ARK - WKAllen1@aol.comExpress Mail Address:
186 Princeton-Hightstown Rd.
Building 3B
Princeton Junction, NJ 08550(609) 243-0330
FAX: (609) 275-1010

FACSIMILE TRANSMISSIONDATE: February 10, 2004TO: Office of Initial Patent Examination's Filing Receipt CorrectionsRECEIVING FAX TELEPHONE NUMBER: (703) 746-9195FROM: **KENNETH WATOV**

TRANSMITTING FAX TELEPHONE NUMBER: (609) 275-1010

NUMBER OF PAGES: 5, including cover sheet

CONFIRMATION TELEPHONE NUMBER: (609) 243-0330

In re Application of:

Applicant	:	Kin P. Cheung
Serial No.	:	10/691,029
Filed	:	October 22, 2003
For	:	PROCESSES FOR HERMETICALLY PACKAGING WAFFER LEVEL MICROSCOPIC STRUCTURES
Examiner	:	(Unknown)
Group Art Unit:	:	2818
Atty. Docket No.	:	879.1.004

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KW021004/8791004.RFC

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Applicant : Kin P. Cheung
Serial No. : 10/691,029
Filed : October 22, 2003
For : PROCESSES FOR HERMETICALLY PACKAGING
WAFER LEVEL MICROSCOPIC STRUCTURES
Examiner : (Unknown)
Group Art Unit : 2818
Atty. Docket No. : 879.1.004

FACSIMILE CERTIFICATE	
DATE	February 10, 2004
I HEREBY CERTIFY THAT, ON THE DATE INDICATED ABOVE, I FACSIMILED THIS PAPER TO THE OFFICE OF INITIAL PATENT EXAMINATION'S FILING RECEIPT CORRECTIONS, FACSIMILE NUMBER 703-746-9195.	
NAME (PRINT)	Kenneth Watov
SIGNATURE	<i>Kenneth Watov</i>

February 10, 2004

VIA FACSIMILE

Office of Initial Patent Examination's Filing Receipt Corrections
P.O. Box 1450
Alexandria, VA 22313-1450

REQUEST FOR CORRECTION OF FILING RECEIPT

Dear Sir:

Transmitted herewith is a marked copy of the Filing Receipt (Confirmation No. 7559) in the above-referenced Application showing changes thereon for correction.

Also enclosed is a copy of the Filing Receipt (Confirmation No. 8105) for Provisional Serial No. 60/420,322 clearly showing a filing date of "10/23/02." Applicant claims the benefit of

- 1 -

KW021004/8791004.RFC

the latter, and requests that the Filing Receipt for the above-captioned Serial No. 10/691,029 be corrected to show the 10/23/02 filing date for 60/420,322.

The undersigned respectfully requests confirmation of the receipt of this facsimile by the Office of Initial Patent Examination.

Respectfully submitted,



Kenneth Watov, Esq.
Registration No. 26,042
Attorney for Applicant

ADDRESS ALL CORRESPONDENCE TO:

Kenneth Watov, Esq.
WATOV & KIPNES, P.C.
P.O. Box 247
Princeton Junction, NJ 08550
(609)243-0330



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 Alexandria, Virginia 22313-1450
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APPL NO.	FILING OR 371 (c) DATE	ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO	DRAWINGS	TOT CLMS	IND CLMS
10/691,029	10/22/2003	2818	525	879.1.004	9	26	5

CONFIRMATION NO. 7559

Kenneth Watov, Esq.
 Watov & Kipnes, P.C.
 P.O. Box 247
 Princeton Junction, NJ 08550

FILING RECEIPT

10/22/2003 10:23:00 AM
 OC000000011773373

Date Mailed: 01/28/2004

Receipt is acknowledged of this regular Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Filing Receipt Corrections, facsimile number 703-746-9195. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

Kin P. Cheung, Hoboken, NJ;

Domestic Priority data as claimed by applicant

This appln claims benefit of 60/430,322 ~~12/02/2002~~ **10/23/02**
~~(*) Data provided by applicant is not consistent with PTO records.~~

Foreign Applications

If Required, Foreign Filing License Granted: 01/28/2004

Projected Publication Date: 06/03/2004

Non-Publication Request: No

Early Publication Request: No

** SMALL ENTITY **

Title

Processes for hermetically packaging wafer level microscopic structures

Preliminary Class

Commissioner for Patents
Washington, DC 20231
www.uspto.gov

APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FL FEE REC'D	ATTY. DOCKET NO	DRAWINGS	TOT CLAIMS	IND CLAIMS
60/420,322	10/23/2002		80	03-046	1		

27461

RUTGERS, THE STATE UNIVERSITY
ATTN: VINCENT SMERAGLIA
58 BEVIER ROAD
PISCATAWAY, NJ 08854

CONFIRMATION NO. 8105

FILING RECEIPT

OC00000009182451

Date Mailed: 12/02/2002

Receipt is acknowledged of this provisional Patent Application. It will not be examined for patentability and will become abandoned not later than twelve months after its filing date. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Filing Receipt Corrections, facsimile number 703-746-9195. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

Kin P. Cheung, Piscataway, NJ;

If Required, Foreign Filing: License Granted: 12/02/2002

Projected Publication Date: None, application is not eligible for pre-grant publication

Non-Publication Request: No

Early Publication Request: No

** SMALL ENTITY **

Title

Method to produce localized vacuum seal at wafer level for low cost high reliability packaging

LICENSE FOR FOREIGN FILING UNDER
Title 35, United States Code, Section 184
Title 37, Code of Federal Regulations, 5.11 & 5.15

GRANTED

DEC